



1NM60-FDQ

Power MOSFET

1A, 600V N-CHANNEL SUPER-JUNCTION MOSFET

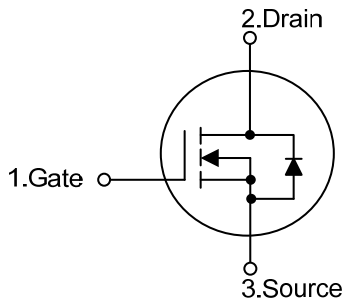
DESCRIPTION

The UTC **1NM60-FDQ** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

FEATURES

- * $R_{DS(ON)} < 4.8\Omega @ V_{GS}=10V, I_D=0.5A$
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

SYMBOL

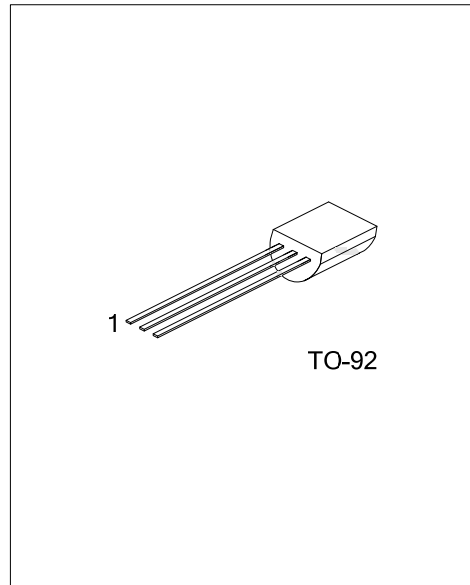


ORDERING INFORMATION

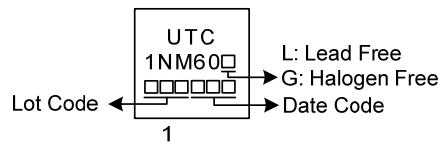
Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
1NM60L-T92-B	1NM60G-T92-B	TO-92	G	D	S	Tape Box
1NM60L-T92-K	1NM60G-T92-K	TO-92	G	D	S	Bulk

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>1NM60G-T92-B</p> <p>(1)Packing Type (2)Package Type (3)Green Package</p>	<p>(1) B: Tape Box, K: Bulk (2) T92: TO-92 (3) G: Halogen Free and Lead Free, L: Lead Free</p>
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■ MARKING



■ ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V_{DSS}	600	V
Gate-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current	I_D	1	A
Pulsed Drain Current (Note 2)	I_{DM}	3	A
Avalanche Energy (Note 3)	E_{AS}	8.2	mJ
Single Pulsed			
Peak Diode Recovery dv/dt (Note 4)	dv/dt	31	V/ns
Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	1.4	W
Junction Temperature	T_J	+150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^\circ\text{C}$

- Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
 3. $L=10\text{mH}$, $I_{AS}=1.7\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\ \Omega$, Starting $T_J = 25^\circ\text{C}$
 4. $I_{SD} \leq 1.0\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ THERMAL DATA

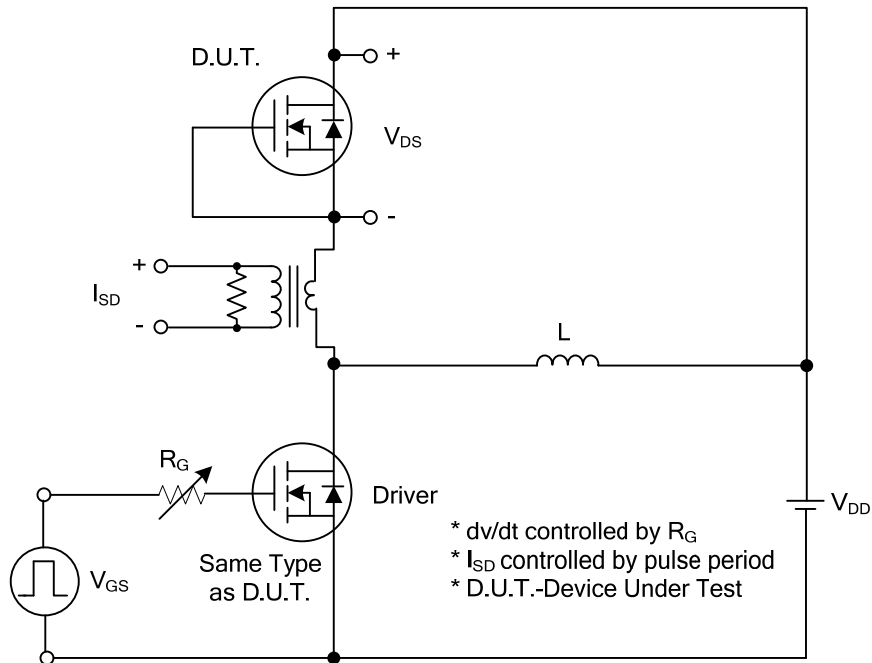
PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	140	$^\circ\text{C}/\text{W}$
Junction to Case	θ_{JC}	80	$^\circ\text{C}/\text{W}$

■ ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$, unless otherwise specified)

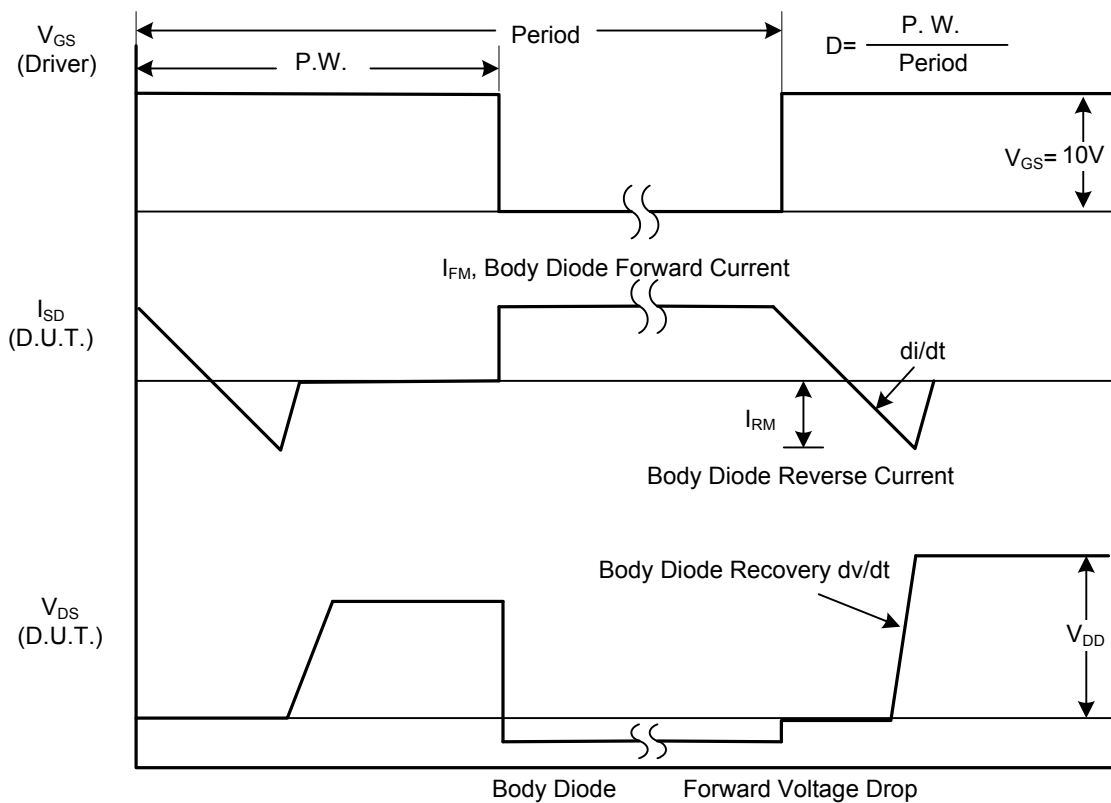
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$	600			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 600\text{V}$, $V_{GS} = 0\text{V}$			10	μA
Gate-Source Leakage Current	I_{GSS}	Forward			100	nA
		Reverse			-100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	2.5		4.5	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{V}$, $I_D = 0.5\text{A}$			4.8	Ω
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{ISS}	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1\text{MHz}$		83		pF
Output Capacitance	C_{OSS}			62.3		pF
Reverse Transfer Capacitance	C_{RSS}			8.2		pF
SWITCHING CHARACTERISTICS						
Total Gate Charge	Q_G	$V_{DS} = 100\text{V}$, $V_{GS} = 10\text{V}$, $I_D = 1\text{A}$, $I_G = 3\text{mA}$ (Note 1, 2)		9.7		nC
Gate-Source Charge	Q_{GS}			3.5		nC
Gate-Drain Charge	Q_{GD}			1.5		nC
Turn-On Delay Time	$t_{D(ON)}$	$V_{DD} = 50\text{V}$, $V_{GS} = 10\text{V}$, $I_D = 1\text{A}$, $R_G = 25\Omega$ (Note 1, 2)		4		ns
Turn-On Rise Time	t_R			15		ns
Turn-Off Delay Time	$t_{D(OFF)}$			16		ns
Turn-Off Fall Time	t_F			10		ns
DRAIN-SOURCE DIODE CHARACTERISTICS						
Maximum Body-Diode Continuous Current	I_S				1.0	A
Continuous Drain-Source Current	I_{SD}				3.0	A
Drain-Source Diode Forward Voltage	V_{SD}	$I_S = 1.0\text{A}$, $V_{GS} = 0\text{V}$			1.4	V
Reverse Recovery Time	t_{rr}	$I_F = 1.0\text{A}$, $V_{DD} = 100\text{V}$		136		ns
Reverse Recovery Charge	Q_{rr}	$di/dt = 100\text{A}/\mu\text{s}$		0.5		μC

- Notes: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.
 2. Essentially independent of operating temperature.

TEST CIRCUITS AND WAVEFORMS

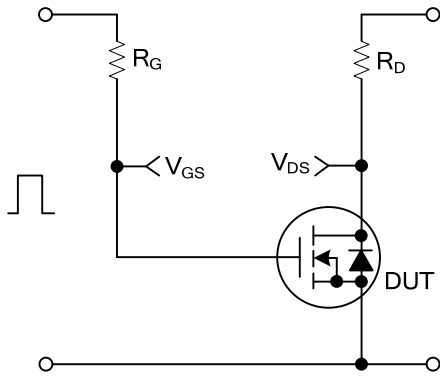


Peak Diode Recovery dv/dt Test Circuit

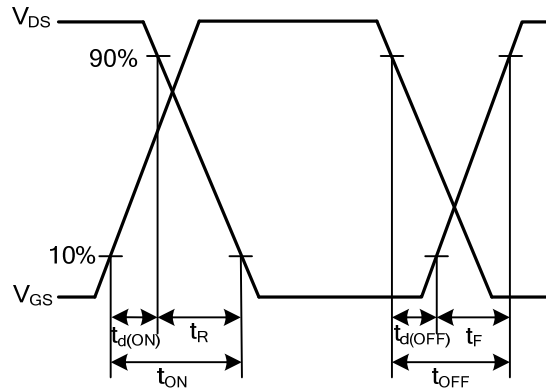


Peak Diode Recovery dv/dt Waveforms

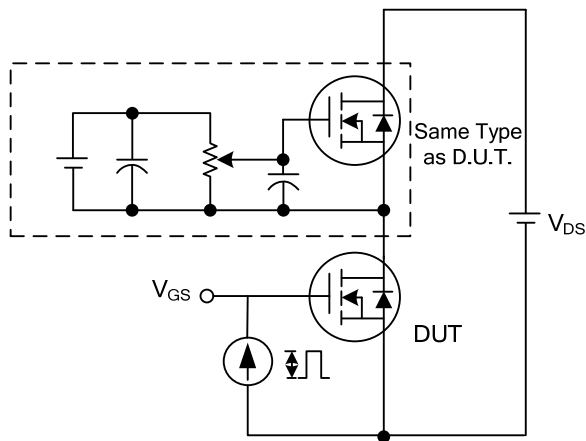
TEST CIRCUITS AND WAVEFORMS (Cont.)



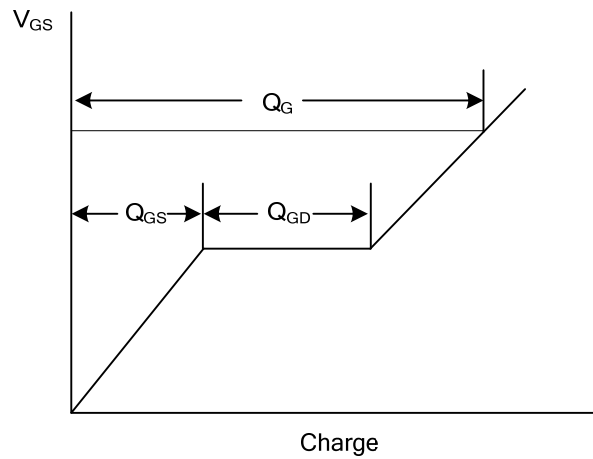
Switching Test Circuit



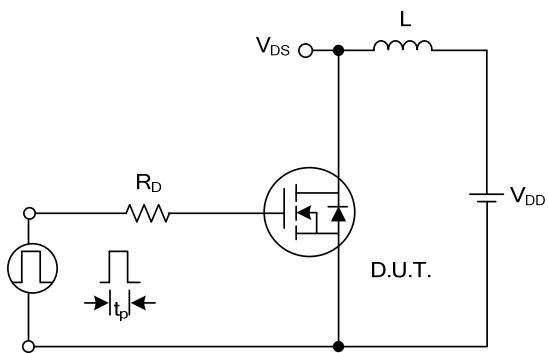
Switching Waveforms



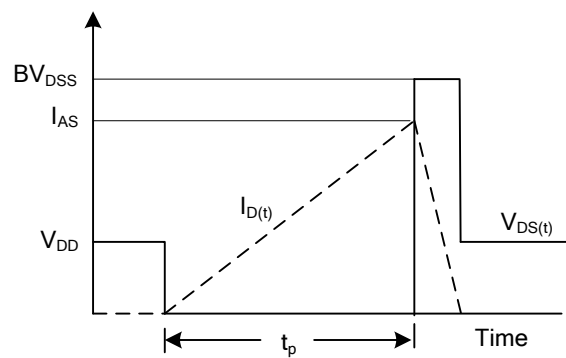
Gate Charge Test Circuit



Gate Charge Waveform

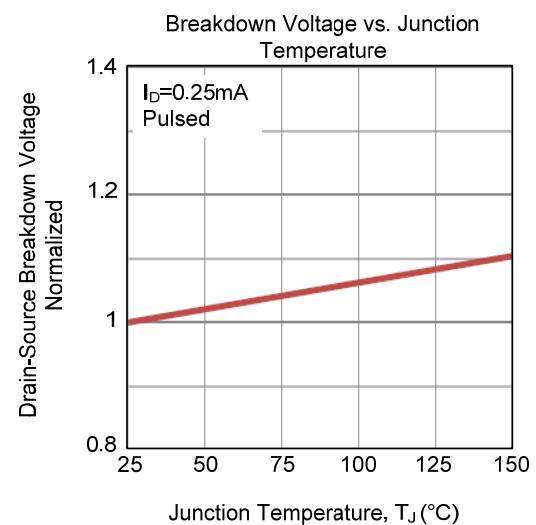
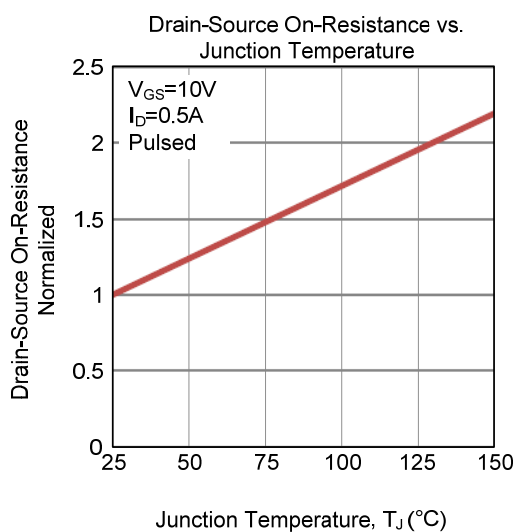
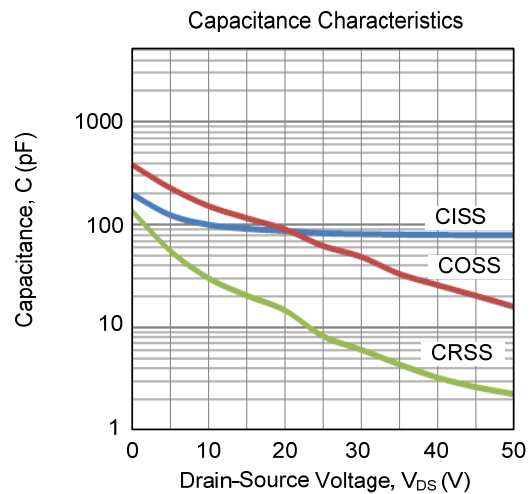
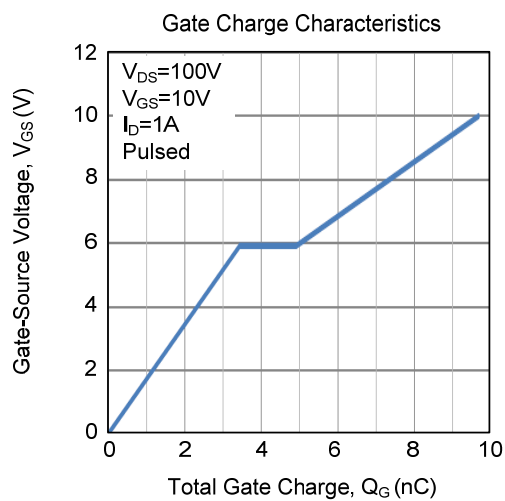
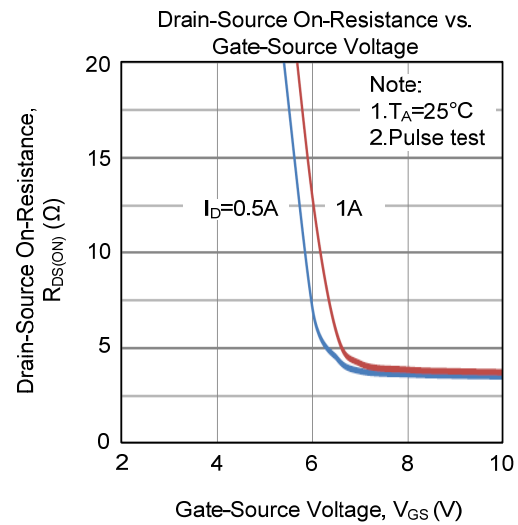
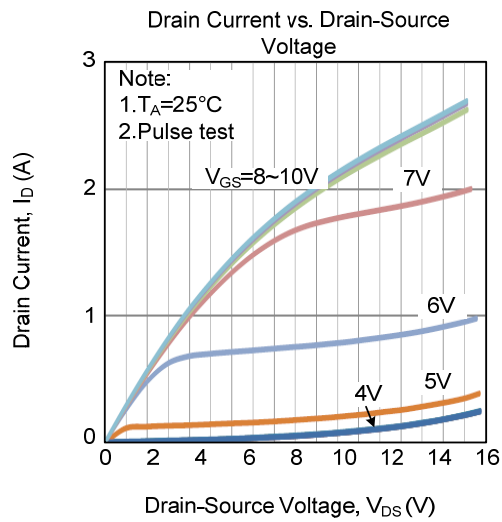


Unclamped Inductive Switching Test Circuit

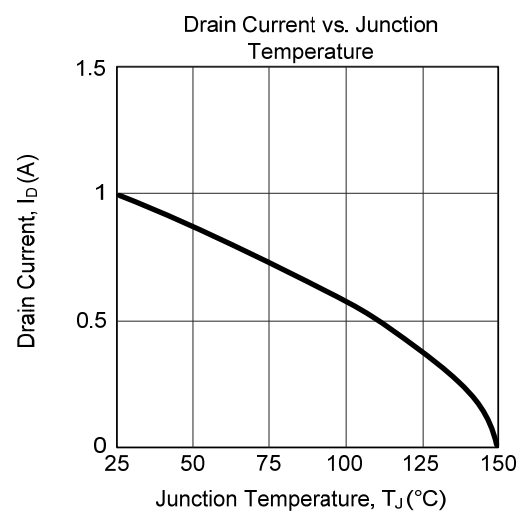
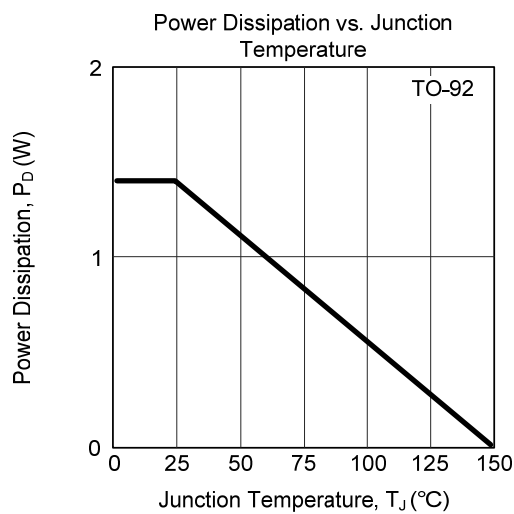
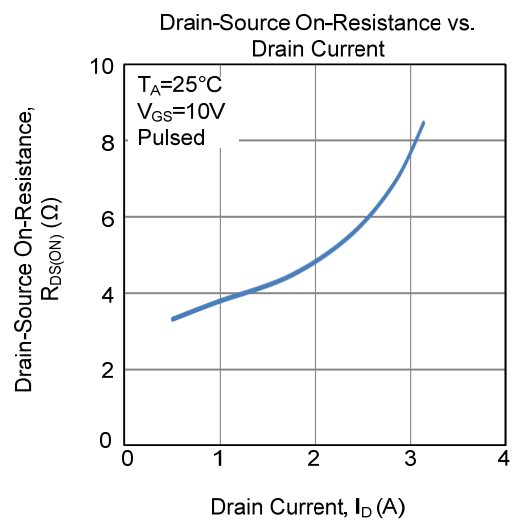
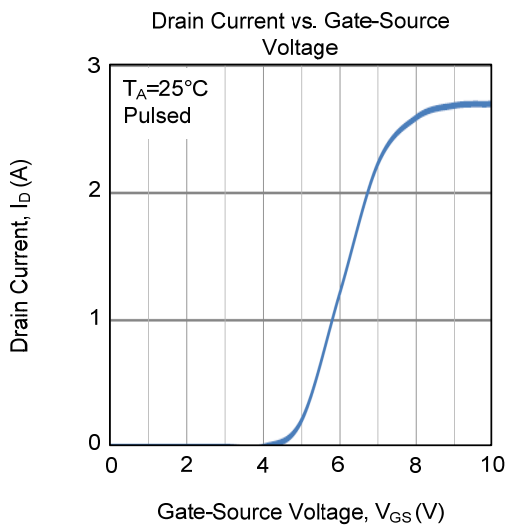
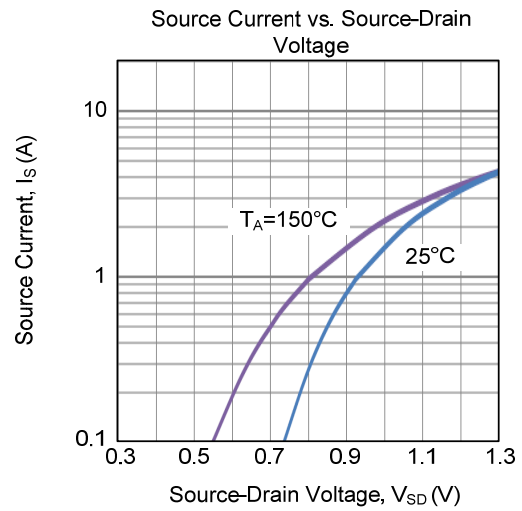
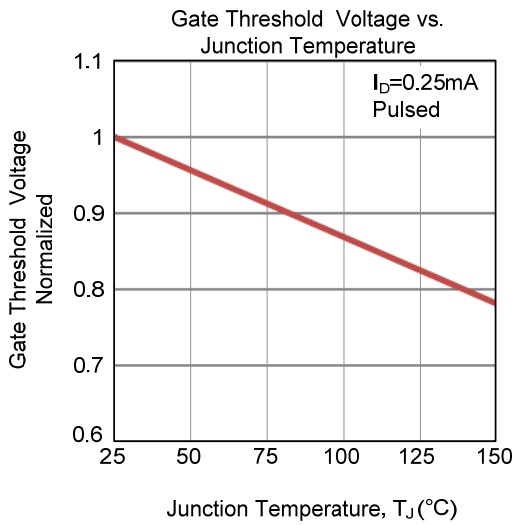


Unclamped Inductive Switching Waveforms

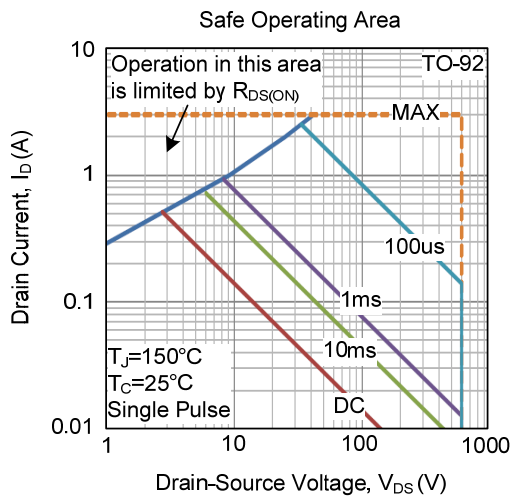
TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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